



# 16A, 35V - 150V Schottky Barrier Surface Mount Rectifier

#### **FEATURES**

- AEC-Q101 qualified
- Low power loss, high efficiency
- Ideal for automated placement
- Guard ring for overvoltage protection
- High surge current capability
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

#### **APPLICATIONS**

- Low voltage, high freq. inverter
- DC/DC converter
- Freewheeling diodes
- Reverse battery protection
- Car lighting

### **MECHANICAL DATA**

- Case: TO-263AB (D<sup>2</sup>PAK)
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: As marked
- Weight: 1.37g (approximately)

KEY PARAMETERS			
PARAMETER	VALUE	UNIT	
I <sub>F</sub>	16	Α	
$V_{RRM}$	35 - 150	V	
I <sub>FSM</sub>	150	Α	
T <sub>J MAX</sub>	150 °C		
Package	TO-263AB (D <sup>2</sup> PAK)		
Configuration	Single die		









TO-263AB (D<sup>2</sup>PAK)



ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25°C unless otherwise noted)									
		MBRS	MBRS	MBRS	MBRS	MBRS	MBRS	MBRS	
PARAMETER	SYMBOL	1635	1645	1650	1660	1690	16100	16150	UNIT
		Н	Н	Н	Н	Н	Н	Н	
Marking code on the device		MBRS 1635	MBRS 1645	MBRS 1650	MBRS 1660	MBRS 1690	MBRS 16100	MBRS 16150	
Repetitive peak reverse voltage	$V_{RRM}$	35	45	50	60	90	100	150	V
Reverse voltage, total rms value	$V_{R(RMS)}$	24	31	35	42	63	70	105	V
Forward current	I <sub>F</sub>	16					Α		
Surge peak forward current, 8.3ms single half sine wave superimposed on rated load	I <sub>FSM</sub>	I <sub>FSM</sub> 150					А		
Peak repetitive reverse surge current <sup>(1)</sup>	I <sub>RRM</sub>	1 0.5					Α		
Peak repetitive forward current (Rated V <sub>R</sub> , Square wave, 20KHz)	I <sub>FRM</sub> 32				Α				
Junction temperature	$T_J$	T <sub>J</sub> -55 to +150			°C				
Storage temperature	T <sub>STG</sub>	-55 to +175			°C				

#### Notes:

1.  $tp = 2.0\mu s$ , 1.0KHz



THERMAL PERFORMANCE				
PARAMETER	SYMBOL	TYP	UNIT	
Junction-to-case thermal resistance	R <sub>eJC</sub>	1.5	°C/W	

PARAMETER		CONDITIONS SYMBOL		TYP	MAX	UNIT
	MBRS1635H MBRS1645H	I <sub>F</sub> = 16A, T <sub>J</sub> = 25°C	V <sub>F</sub>	-	0.63	V
	MBRS1650H MBRS1660H			-	0.75	V
	MBRS1690H MBRS16100H			-	0.85	V
<b>5</b> (1)	MBRS16150H			-	0.95	V
Forward voltage <sup>(1)</sup>	MBRS1635H MBRS1645H	I <sub>F</sub> = 16A, T <sub>J</sub> = 125°C		-	0.57	V
	MBRS1650H MBRS1660H			-	0.65	V
	MBRS1690H MBRS16100H			-	0.82	V
	MBRS16150H			-	0.92	V
Reverse current @ rated V <sub>R</sub> <sup>(2)</sup>	MBRS1635H MBRS1645H MBRS1650H MBRS1660H	T <sub>J</sub> = 25°C	I <sub>R</sub>	-	500	μΑ
	MBRS1690H MBRS16100H			-	300	μΑ
	MBRS16150H			-	100	μΑ
	MBRS1635H MBRS1645H			-	15	mA
	MBRS1650H MBRS1660H	T <sub>J</sub> = 125°C		-	10	mA
	MBRS1690H MBRS16100H				7.5	mA
	MBRS16150H			-	5	mA

### Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION				
ORDERING CODE <sup>(1)</sup>	PACKAGE	PACKING		
MBRS16xH	TO-263AB (D <sup>2</sup> PAK)	800 / Tape & Reel		

### Notes:

1. "x" defines voltage from 35V(MBRS1635H) to 150V(MBRS16150H)

Fig.2 Typical Junction Capacitance



### **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

Fig.1 Forward Current Derating Curve

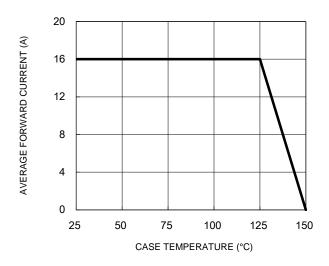
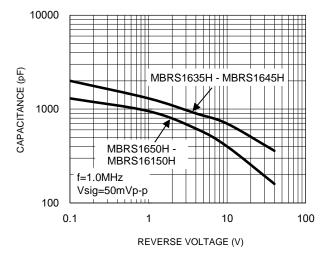
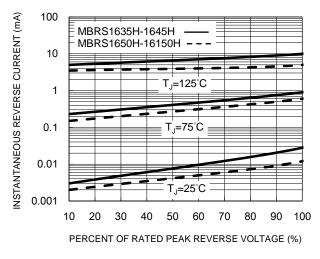


Fig.3 Typical Reverse Characteristics



**Fig.4 Typical Forward Characteristics** 



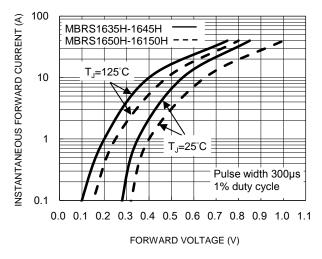
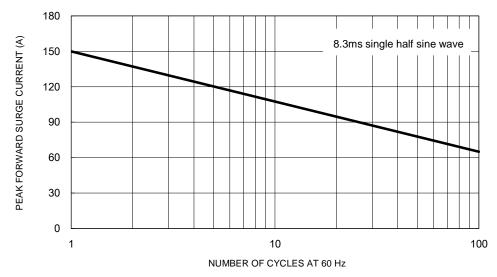


Fig.5 Maximum Non-Repetitive Forward Surge Current



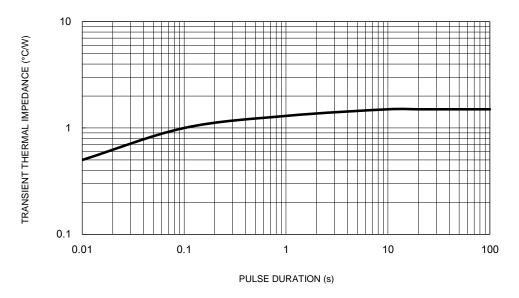


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### **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

Fig.6 Typical Transient Thermal Impedance

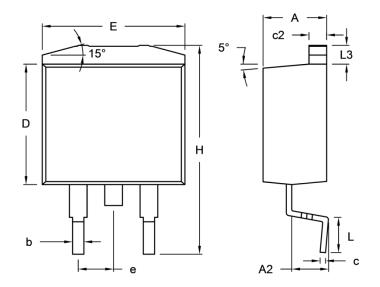




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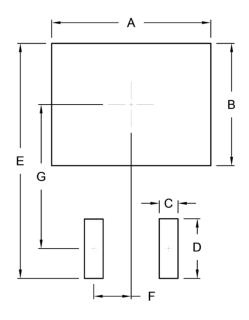
### **PACKAGE OUTLINE DIMENSIONS**

# TO-263AB (D<sup>2</sup>PAK)



DIM.	Unit (mm)		Unit (	(inch)
DIW.	Min.	Max.	Min.	Max.
Α	4.44	4.70	0.175	0.185
A2	2.03	2.79	0.080	0.110
b	0.68	0.94	0.027	0.037
С	0.36	0.53	0.014	0.021
c2	1.14	1.40	0.045	0.055
D	8.25	9.25	0.325	0.364
Е	-	10.50	-	0.413
е	2.41	2.67	0.095	0.105
Н	14.60	15.88	0.575	0.625
L	2.29	2.79	0.090	0.110
L3	1.14	1.40	0.045	0.055

### **SUGGESTED PAD LAYOUT**



Symbol	Unit (mm)	Unit (inch)
Α	10.80	0.425
В	8.30	0.327
С	1.27	0.050
D	4.05	0.159
E	15.95	0.628
F	2.54	0.100
G	9.775	0.385

### **MARKING DIAGRAM**



P/N = Marking Code G = Green Compound

YWW = Date Code F = Factory Code



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